

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Todd O. Bolken

Serial No.: 10/791,192

Filed: March 2, 2004

For: TWO-STAGE TRANSFER MOLDING
DEVICE TO ENCAPSULATE MMC
MODULE

Confirmation No.: 1966

Examiner: D. Zarncke

Group Art Unit: 2891

Attorney Docket No.: 2269-4794.4US
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Notice of Allowance Mailed:

May 1, 2007

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July 25, 2007

**FEE ADDRESSEE FOR RECEIPT OF PTO NOTICES
RELATING TO MAINTENANCE FEES**

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

1. This letter is to specify that the FEE ADDRESSEE for this patent is:

MICRON TECHNOLOGY, INC.

Mail Stop 525
8000 South Federal Way
Boise, Idaho 83707-0006

2. The Customer Number for the Fee Addressee is **26809**.
3. Any prior FEE ADDRESSEE for this patent is hereby revoked.
4. It is certified that the person whose signature appears below has the authority to change the FEE ADDRESSEE for this patent.

Respectfully submitted,



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JRD/djp:lmh

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